(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
25 February 2010 (25.02.2010)

PCT

(10) International Publication Number
WO 2010/019983 A1

(51) **International Patent Classification**:
B41J 2/14 (2006.01) ***B41J 2/16*** (2006.01)
B32B 37/00 (2006.01)

(21) **International Application Number**:
PCT/AU2008/001197

(22) **International Filing Date**:
19 August 2008 (19.08.2008)

(25) **Filing Language**: English

(26) **Publication Language**: English

(71) **Applicant** *(for all designated States except US)*: **SILVERBROOK RESEARCH PTY LTD** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(72) **Inventors; and**

(75) **Inventors/Applicants** *(for US only)*: **SLEIJPEN, Stephen, John** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **ANDREW, James** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **BOWYER, Graeme, Kenneth** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **GRANGER, William** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **WASZCZUK, Jan** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **BURKE, David, Oliver** [IE/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **STRUDWICKE, Craig, Donald** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **THELANDER, Jason, Mark** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(74) **Agent**: **SILVERBROOK RESEARCH PTY LTD**; 393 Darling Street, Balmain, New South Wales 2041 (AU).

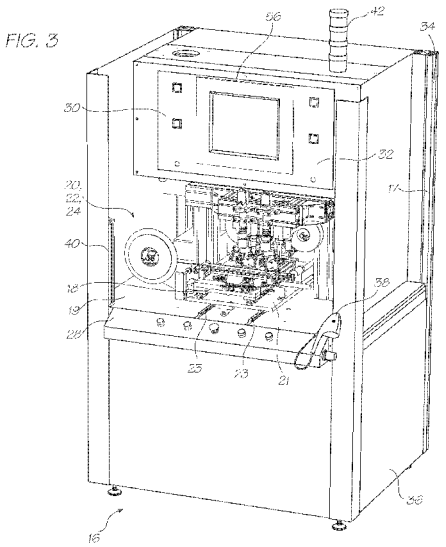
(81) **Designated States** *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) **Designated States** *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, NO, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*

(54) **Title**: LAMINATING APPARATUS FOR A PRINTHEAD CARRIER SUB-ASSEMBLY



(57) **Abstract**: The invention relates to a laminating apparatus for laminating a printhead integrated circuit (IC) carrier sub-assembly and a lamination film. The apparatus includes a lamination support for receiving the carrier, a lamina supply for supplying a lamina defining said lamination film, and an alignment mechanism configured to align the lamination film with the IC carrier sub-assembly. Also included is a bonding apparatus configured to bond the lamination film to the IC carrier sub-assembly, and a control system to control operation of the lamina supply, alignment mechanism and bonding apparatus to facilitate automatic bonding of the lamination film to the surface of the carrier.

WO 2010/019983 A1